2SC5392

Silicon NPN triple diffusion planar type

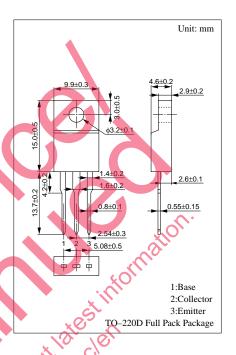
For high breakdown voltage high-speed switching

Features

- High-speed switching
- High collector to base voltage V_{CBO}
- Wide area of safe operation (ASO)
- Satisfactory linearity of foward current transfer ratio h_{FE}
- Dielectric breakdown voltage of the package: > 5kV

Absolute Maximum Ratings $(T_C=25^{\circ}C)$

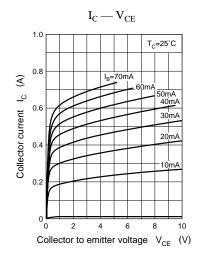
Parameter	Symbol	Ratings	Unit	
Collector to base voltage	V _{CBO}	800	V	
C-11	V _{CES}	800	V	
Collector to emitter voltage	V _{CEO}	500	V	
Emitter to base voltage	V _{EBO}	8	V	
Peak collector current	I _{CP}	3.0	A	
Collector current	$I_{\rm C}$	1.5	A	
Base current	I _B	0.5	A	
Collector power T _C =25°C		25	W	
dissipation Ta=25°C	P_{C}	2.0	W	
Junction temperature	$T_{\rm j}$	150	°C	
Storage temperature	T _{stg}	-55 to +150	°C	

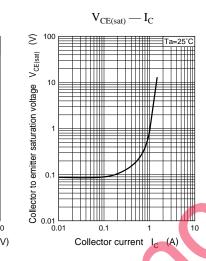


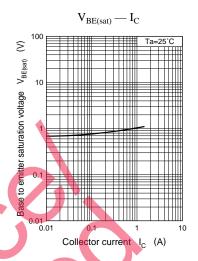
Electrical Characteristics (T_C=25°C)

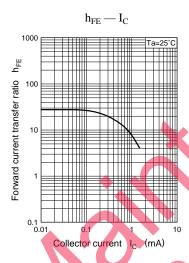
Parameter	Symbol	Conditions	min	typ	max	Unit
Collector cutoff current	I_{CBO}	$V_{CB} = 800V, I_E = 0$			100	μΑ
Emitter cutoff current	I_{EBO}	$V_{EB} = 5V, I_C = 0$			100	μΑ
Collector to emitter voltage	V _{CEO}	$I_C = 10 \text{mA}, I_B = 0$	500			V
Forward current transfer ratio	h _{FE} ()	$V_{CE} = 5V, I_{C} = 0.1A$	15			
	h _{FE2}	$V_{CE} = 5V, I_{C} = 0.6A$	8			
Collector to emitter saturation voltage	V _{CE(sat)}	$I_C = 0.6A, I_B = 0.17A$			1.0	V
Base to emitter saturation voltage	V _{BE(sat)}	$I_C = 0.6A, I_B = 0.17A$			1.5	V
Transition frequency	f_T	$V_{CE} = 10V, I_{C} = 0.1A, f = 1MHz$		20		MHz
Turn-on time	t _{on}	$I_C = 0.6A, I_{B1} = 0.17A, I_{B2} = -0.34A,$ $V_{CC} = 200V$			1.0	μs
Storage time	t _{stg}				3.0	μs
Fall time	t _f				0.3	μs

Power Transistors 2SC5392









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